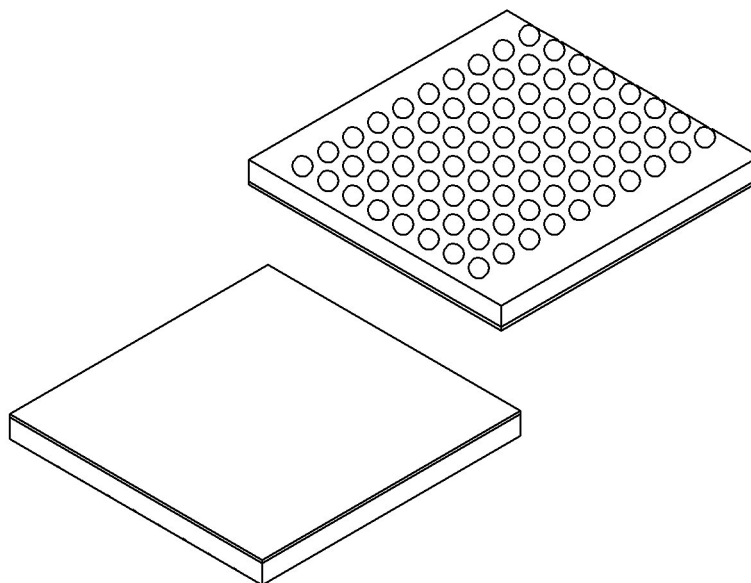


80-Ball Wafer Level Chip Scale Package (6SW) - 3.513x3.593x0.446 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	80		
Pitch	e	0.35 BSC		
Overall Height	A	0.407	0.446	0.485
Ball Height	A1	0.122	0.152	0.182
Backside Coating Thickness	M	0.04 REF		
Wafer Thickness	S	0.229	0.254	0.279
Overall Length	D	3.593 BSC		
Ball Array Length	D1	3.150 BSC		
Overall Width	E	3.513 BSC		
Ball Array Width	E1	2.450 BSC		
Ball Diameter	b	0.188	0.218	0.248

Notes:

- Pin 1 visual index feature may vary but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.